

SEMI GLOBAL UPDATE

February 6, 2024

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What's New at SEMI



Heterogeneous Integration

SEMI and UCLA Offer Guide to Facilitate Onshoring Advanced Packaging Facilities in the U.S.

"The MRHIEP drills down into operational objectives by examining current capabilities and highlighting ...," said Melissa Grupen-Shemansky, SEMI CTO.



Market Research

Podcast: Growth Ahead for Semiconductor Market – Insights at Industry Strategy Symposium 2024

Tseng, Senior Director of MIT, and Skvortsova, an MIT Market Research Analyst, recap key industry developments in 2023 before providing a look at ...



Semiconductor Design

D2S CEO Aki Fujimura: Curvy Design's Time Has Come

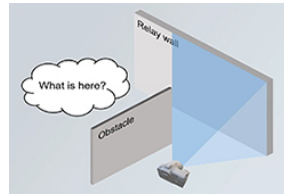
Curvilinear target shapes are manufacturable as targeted – that is, the target shape is achievable, including the rounding that takes place during manufacturing.



Standards

SEMI China EHS Workshop Achieves Significant Milestones

Notably, the workshop marked the inaugural attempt to integrate industry and research institutions, including the university, to address EHS concerns.



SEMI-Related

Infrared Sensors Can Now Peer Around Corners

Non-line-of-sight imaging is no longer restricted to visible wavelengths of light.

Upcoming Events/Webinars

- | | |
|----------|--|
| Feb. 22 | Phil Kaufman Award & Banquet
San Jose, California Pacific Time |
| Feb. 22 | Standardizing the Semiconductor Manufacturing Backend
Virtual Pacific Time |
| Mar. 6-8 | Industry Strategy Symposium Europe (ISS Europe)
Vienna, Austria Central European Time |

[More events](#)

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